

ABSTRACT

A method for manufacturing a ceramic circuit substrates having a high-density conductive pattern, as its internal conductor, formed by a film-intaglio-transfer-printing method is provided. The conductive pattern is temporarily transfer-printed on a heat-resistant substrate coated with an adhesive layer. An un-sintered ceramic green sheet is stacked on a surface of the conductive patterns of the heat-resistant substrate, and then, the conductive pattern is transfer-printed again onto the un-sintered ceramic green sheet like being embedded by heat-pressing. Consequently, the conductive pattern is formed on the green sheet. This then has a binder removed and is sintered, and provides the ceramic circuit substrate having the fine, high-density conductive patterns, as the internal conductor, formed by the film-intaglio-transfer-printing method